IPC ASSOCIATION CONNECTED ELECTRONICS INDUST.	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier Info	rmation						·							
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2023-06-08			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Repro	esentative*		Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site	7	Weight*	UOM	Unit Type
		MC7905CD2TR4G ANA 1A		ANA 1A 5V NEGA	NA 1A 5V NEGATIVE VREG		2023-06-08		N	MY1		909.21	mg	Each
	ng Proccess Informa												·	·
ž į			derminal Base Alloy J-STD-020 MSL		L Rating				e Max Time at Peak					
Matte	Tin (Sn) - annealed	C	U Alloy	1			260		C	30	secon	ds 3		
omments														
vel 1 - maximun	n time at peak temperatı	are during sol	dering is 10-3	30 seconds										
or more informa	ation regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cornel to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	A	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame	340.51	mg	В	Nickel (Ni)	7440-02-0		1.0215	mg
			Supplier	Copper (Cu)	7440-50-8		339.4885	mg
Mold Compound-Black	529.31	mg		Epoxy resin	proprietary data		26.4655	mg
			Supplier	Phenolic Resin	Proprietary Data		26.4655	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.5862	mg
			Supplier	Carbon Black (C)	1333-86-4		2.6465	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		463.1462	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg